

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Syed S. Ahmad

Serial No.: 09/943,967

Filed: August 30, 2001

For: APPARATUS AND METHOD FOR
CONTROLLING THE DEPTH OF
IMMERSION OF A SEMICONDUCTOR
ELEMENT IN AN EXPOSED SURFACE
OF A VISCOUS FLUID

Examiner: Unknown

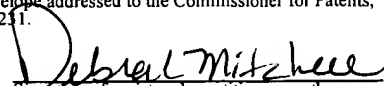
Group Art Unit: 1734

Attorney Docket No.: 3428.2US (97-828.2)

CERTIFICATE OF MAILING

I hereby certify that this paper or fee along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

November 27, 2001
Date of Deposit


Signature of registered practitioner or other
person having reasonable basis to expect mailing
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C.F.R. § 1.8(a)(1)(ii)

Debra L. Mitchell
Typed/printed name of person whose signature is
contained above

TRANSMITTAL OF FORMAL DRAWINGS

Commissioner for Patents
Washington, D.C. 20231

Sir:

Attached please find the formal drawings for this application.

Respectfully submitted,



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Attorney for Applicant
TRASKBRITT
P. O. Box 2550
Salt Lake City, Utah 84110-2550
Telephone: (801) 532-1922

Date: November 27, 2001
KWP/dn

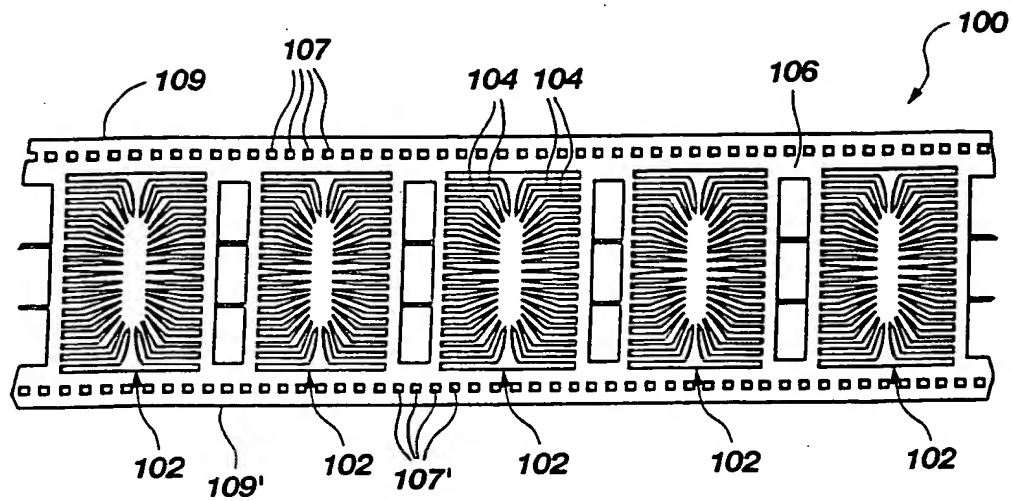


Fig. 1

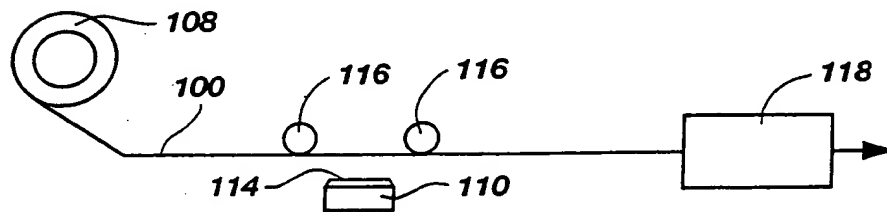


Fig. 2

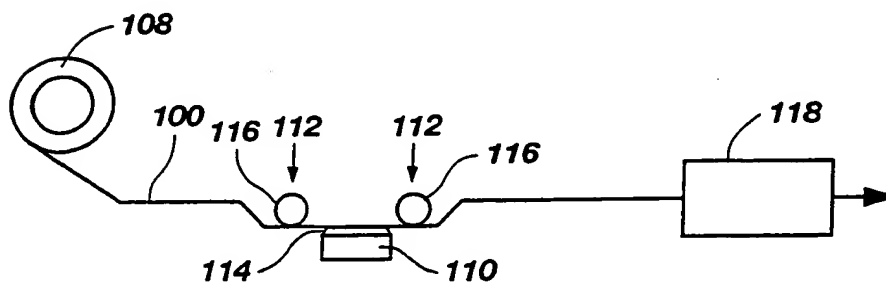


Fig. 3

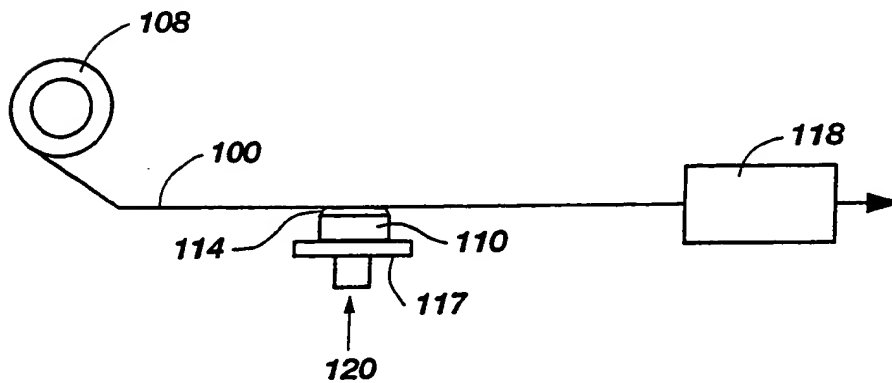


Fig. 4

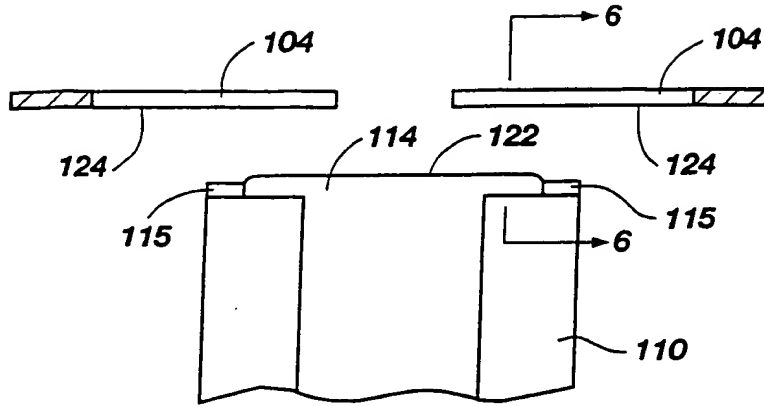


Fig. 5

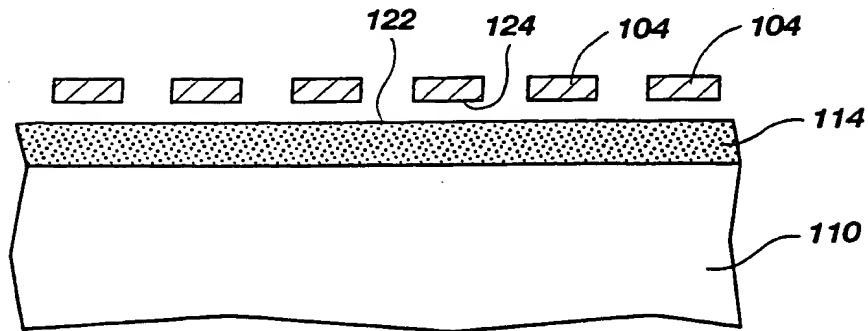


Fig. 6

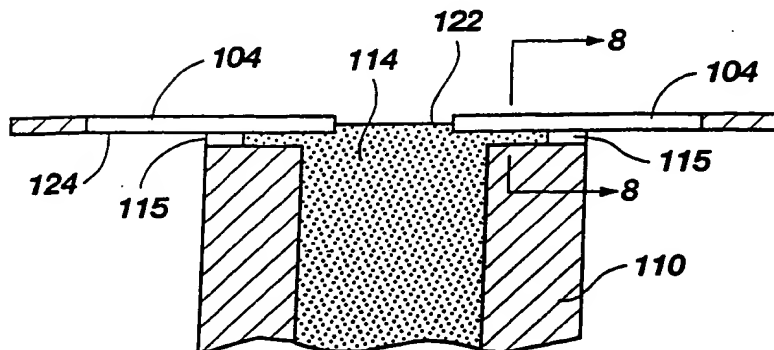


Fig. 7

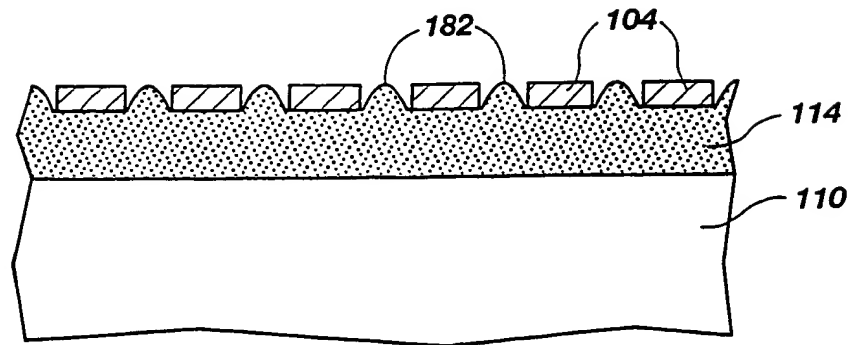


Fig. 8

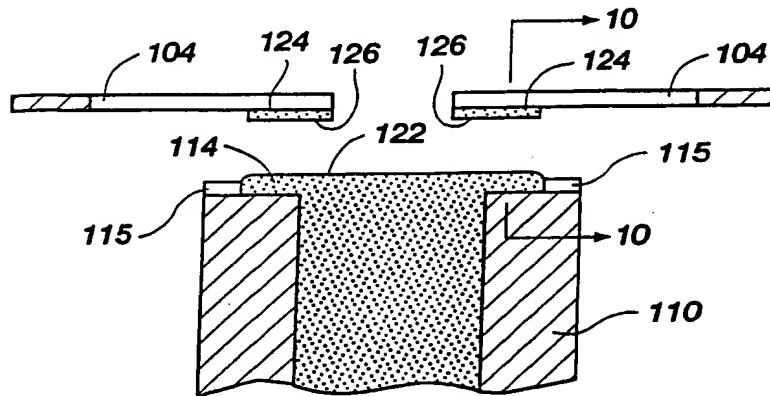


Fig. 9

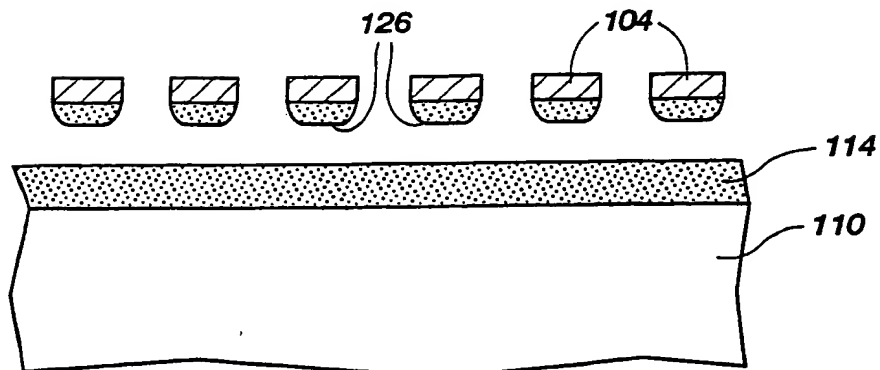


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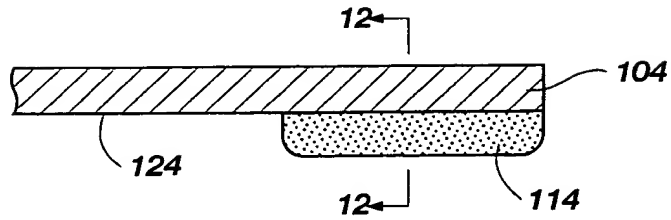


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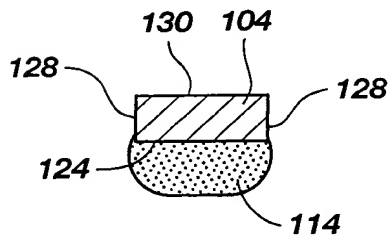


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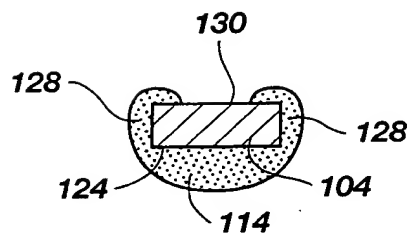


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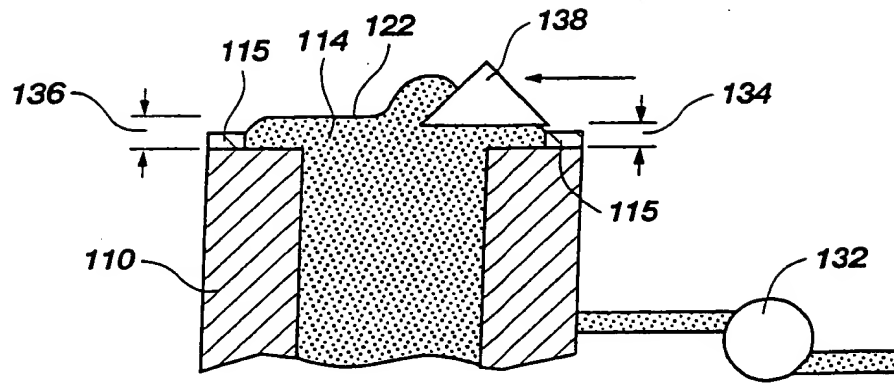


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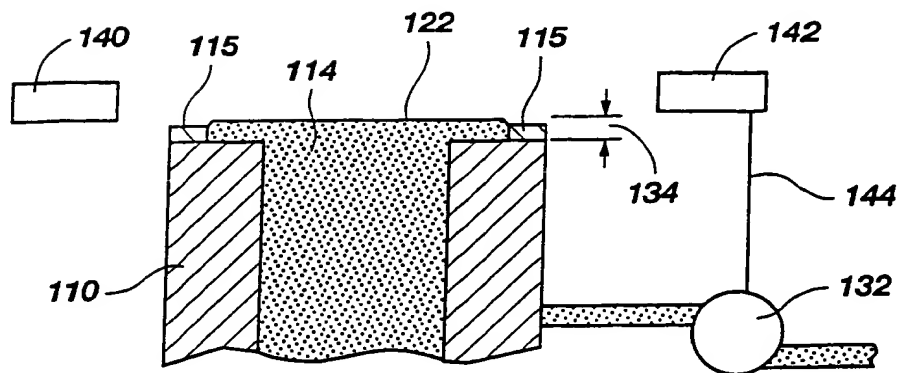


Fig. 15

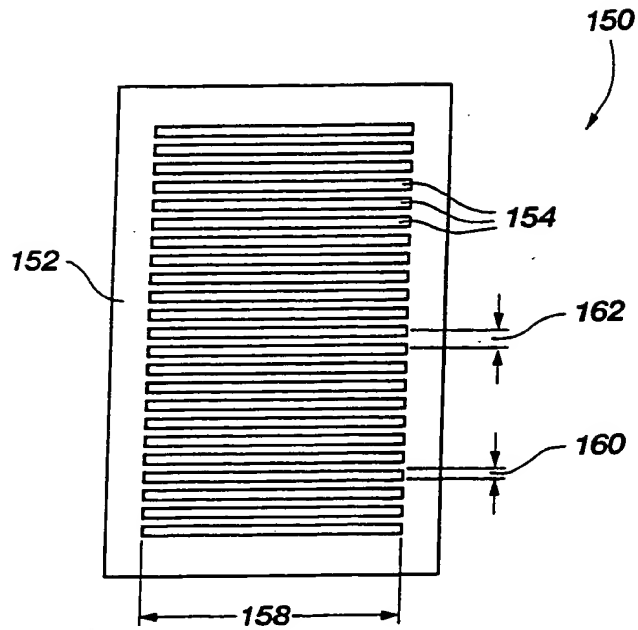


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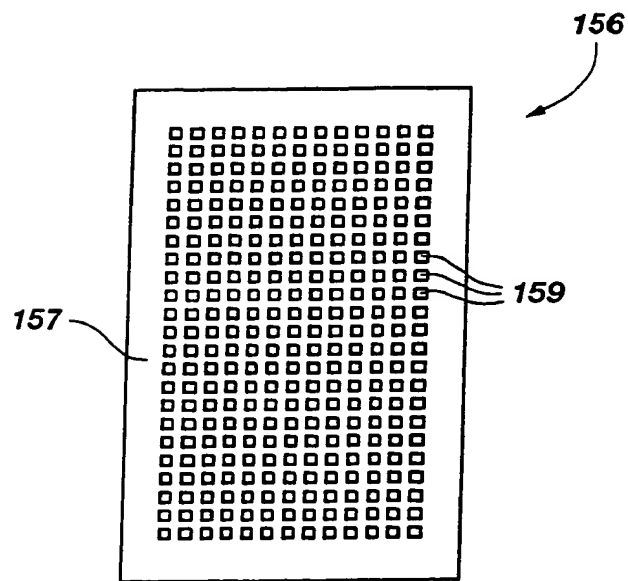


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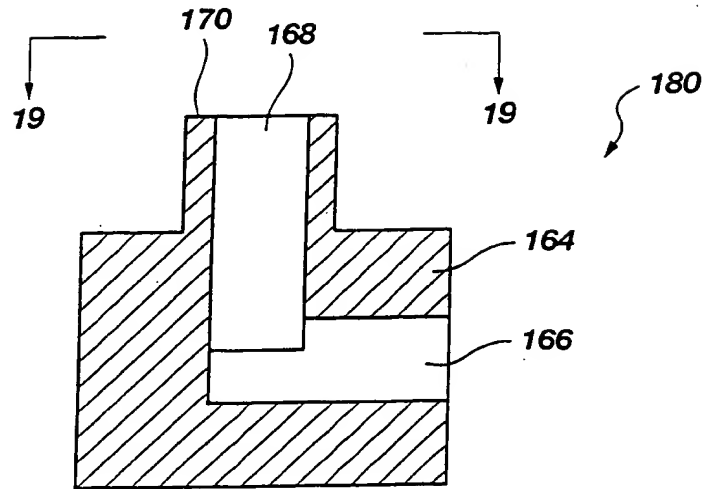


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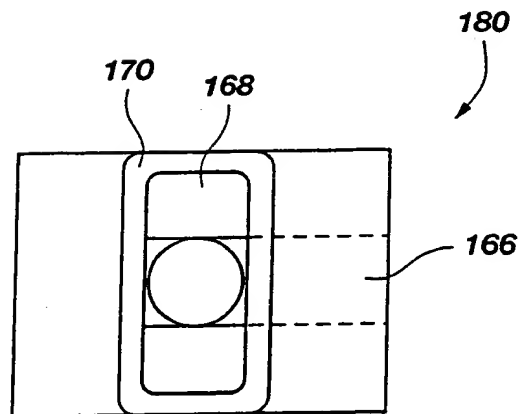


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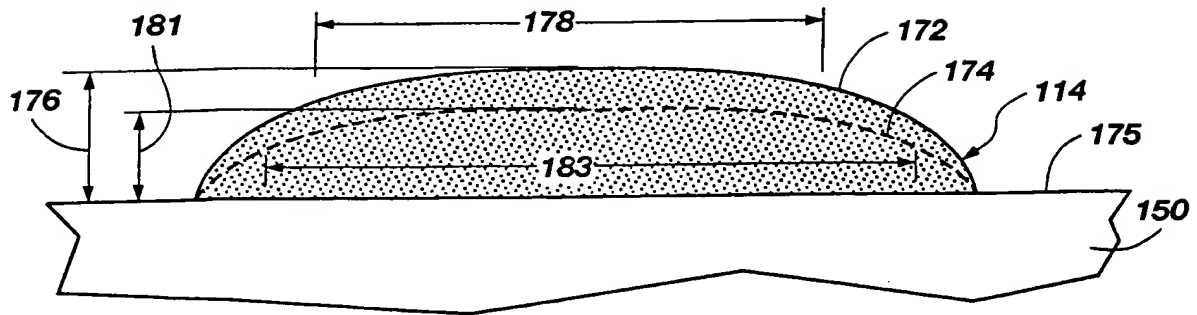


Fig. 20

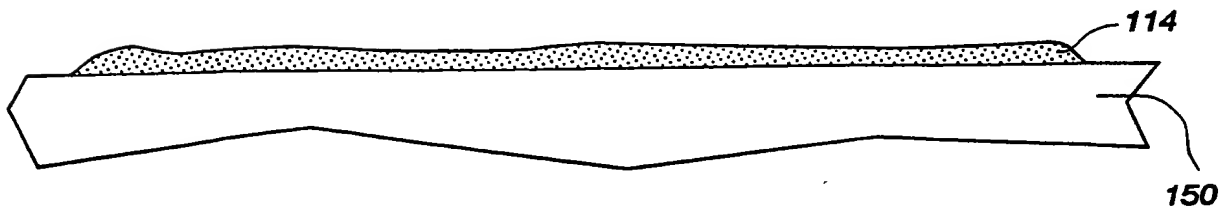


Fig. 21

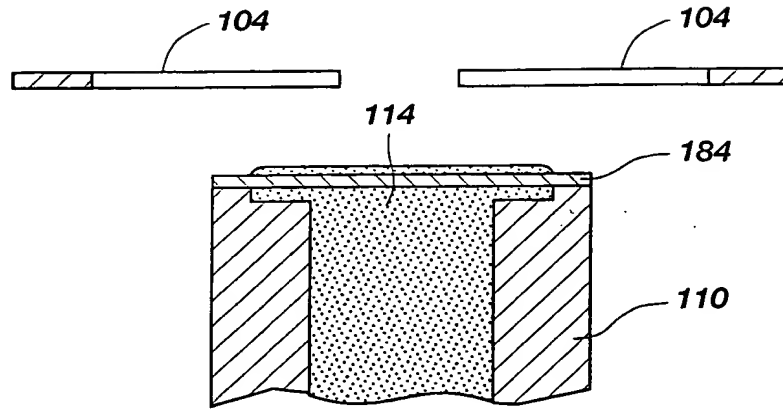


Fig. 22

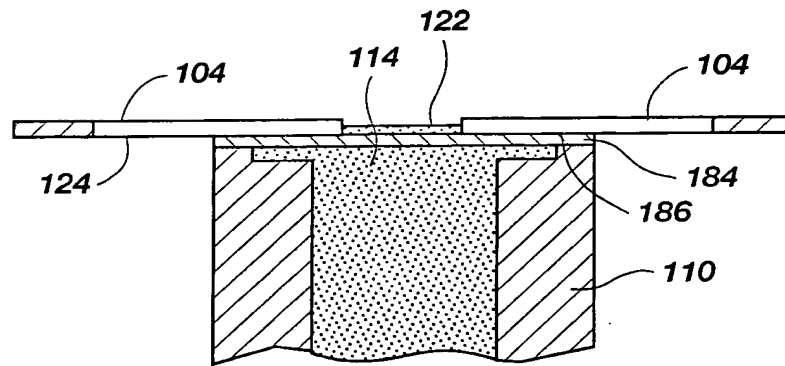


Fig. 23

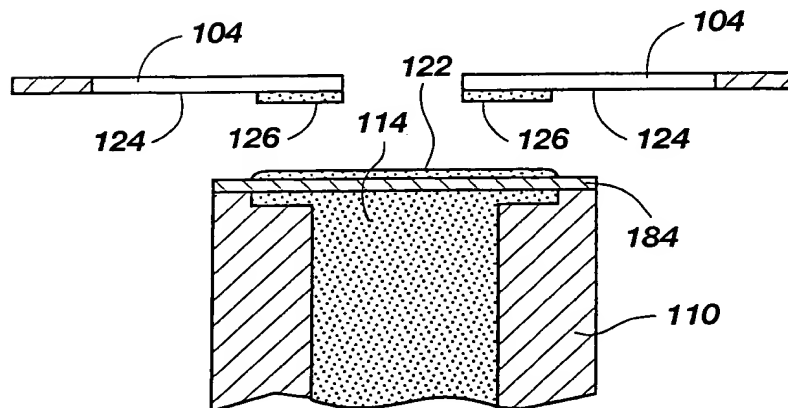


Fig. 24

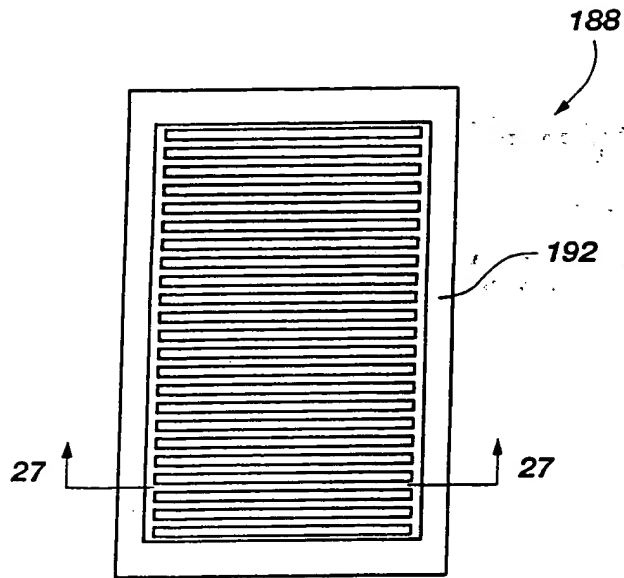


Fig. 25

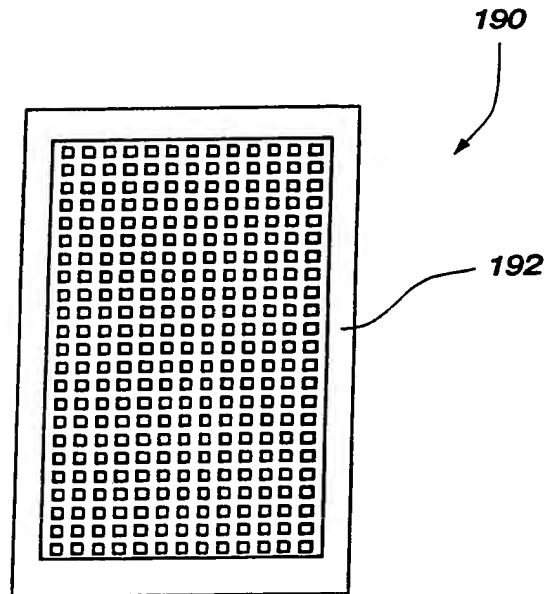


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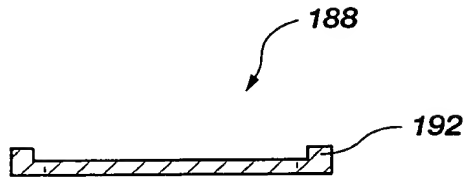


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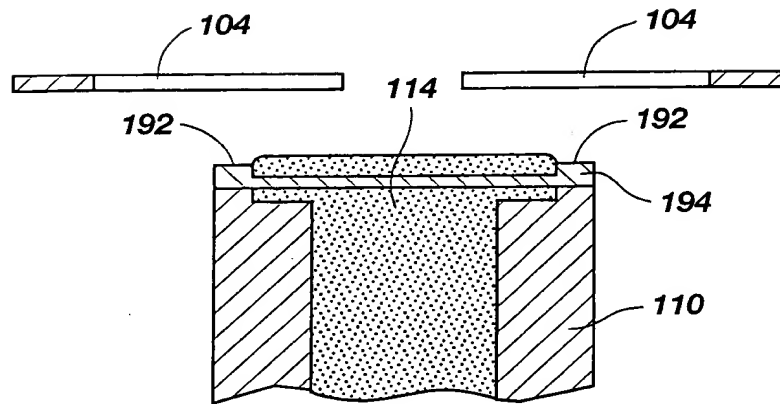


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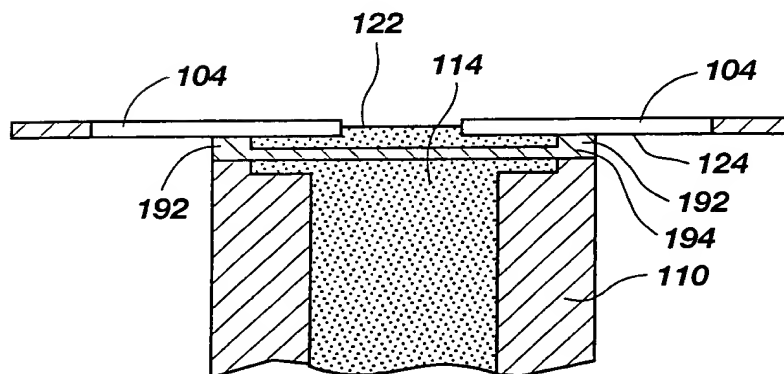


Fig. 29

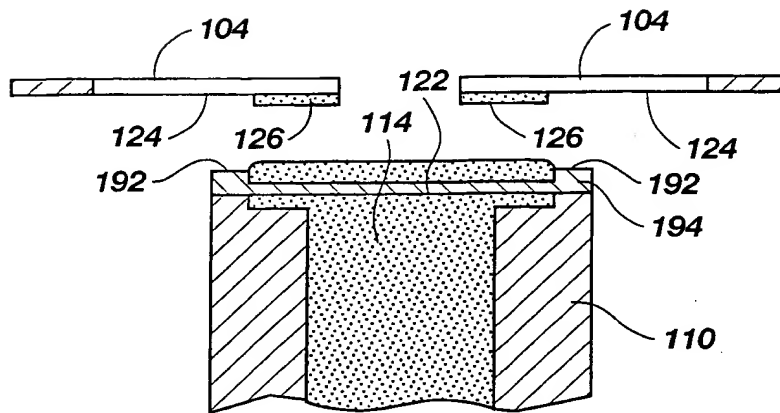


Fig. 30

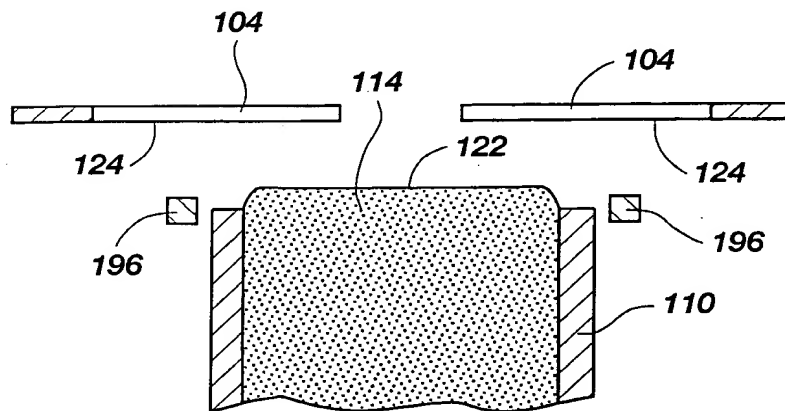


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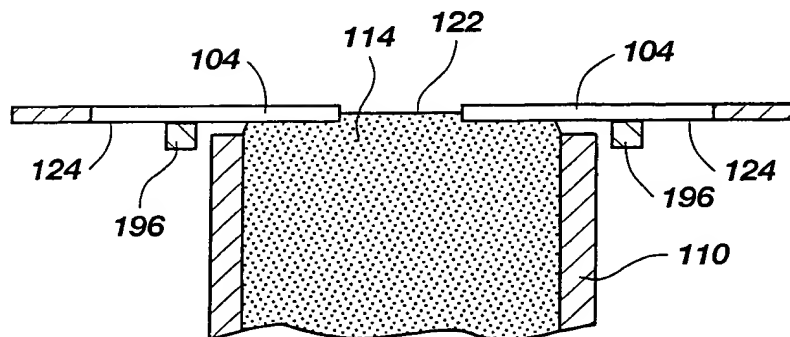


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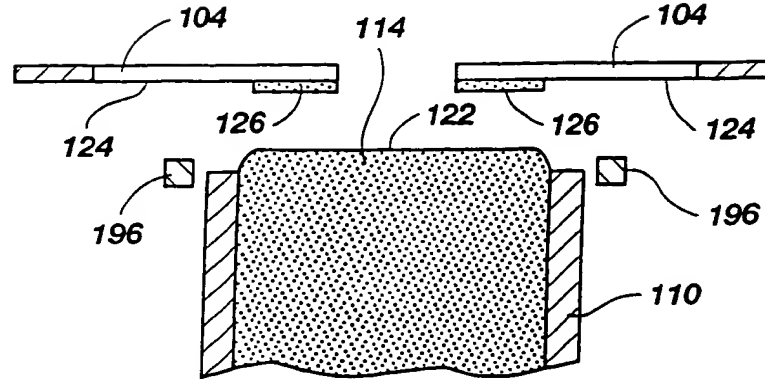


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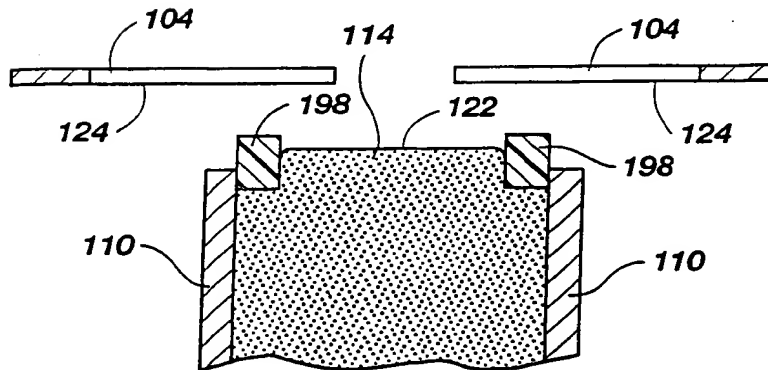


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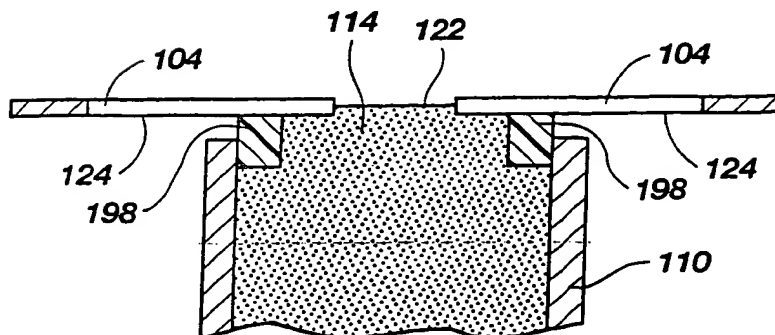


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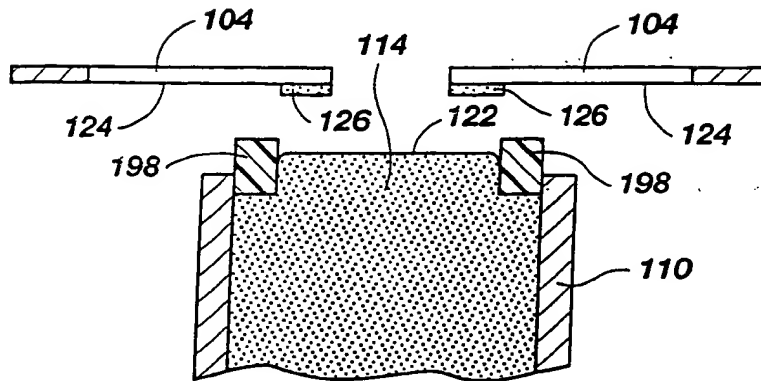


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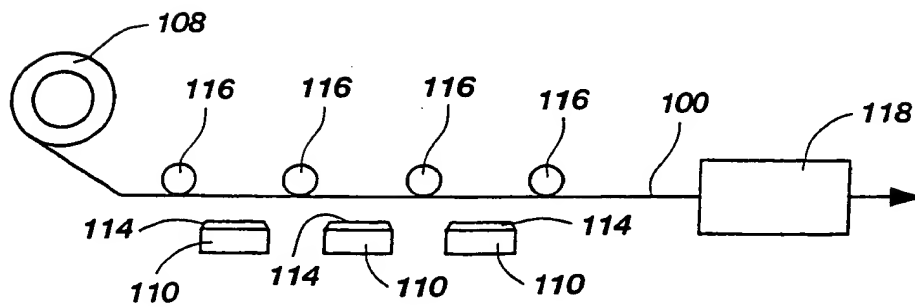


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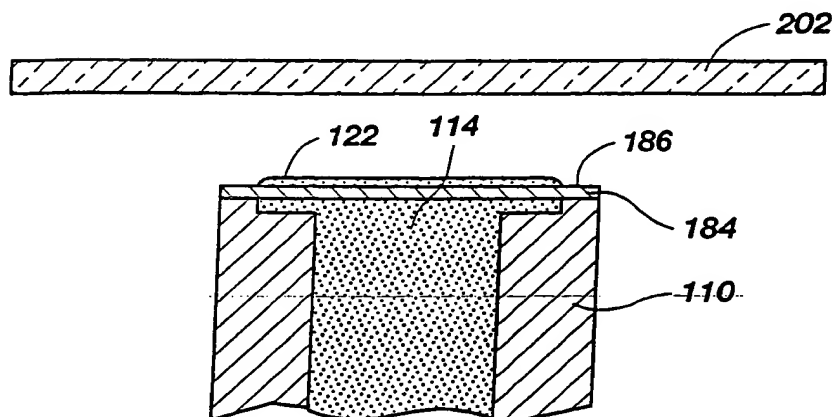


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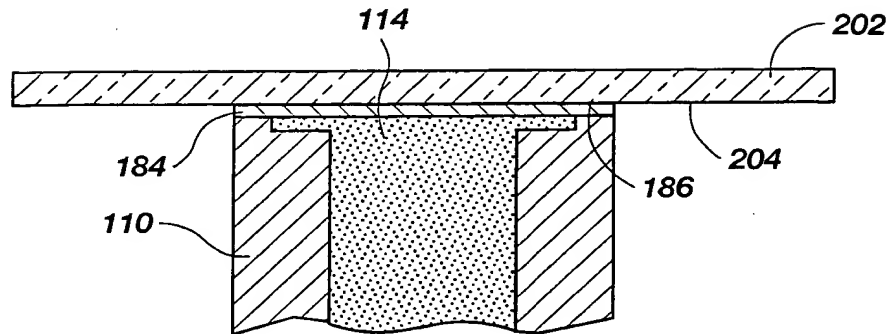


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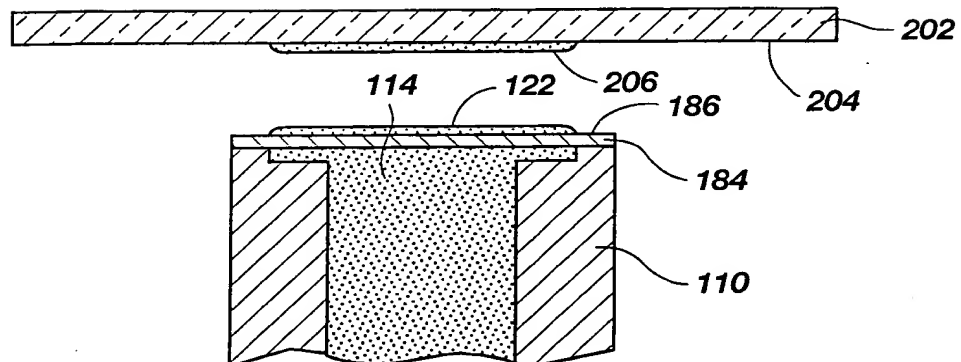


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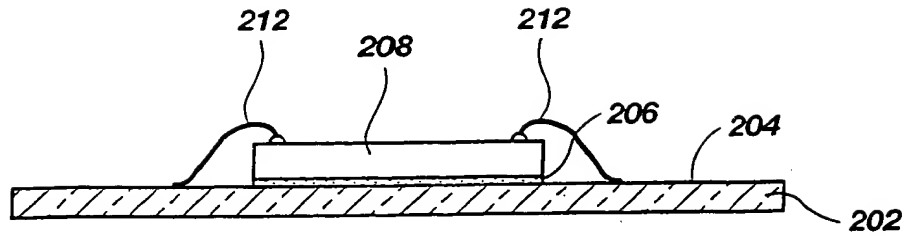


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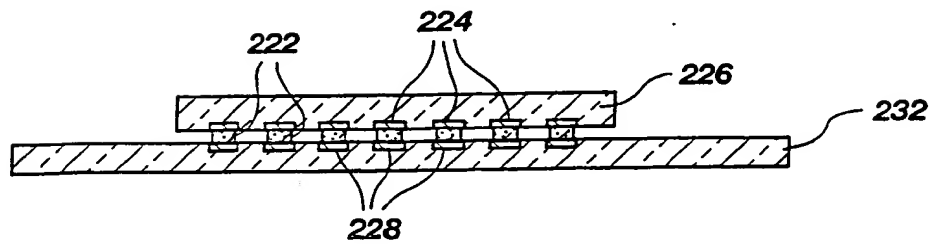


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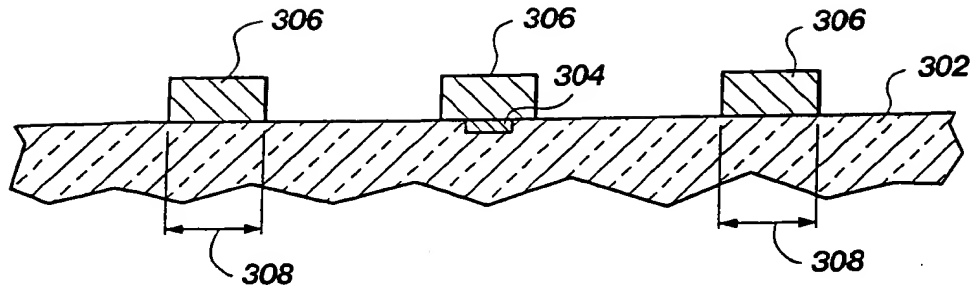


Fig. 43
(PRIOR ART)

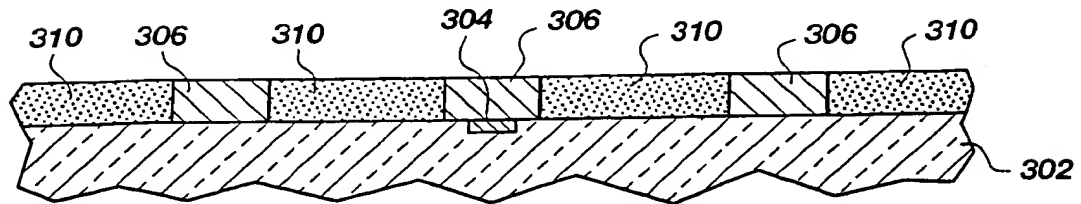


Fig. 44
(PRIOR ART)

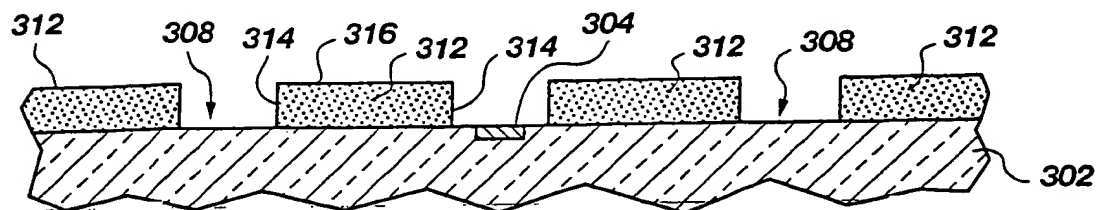


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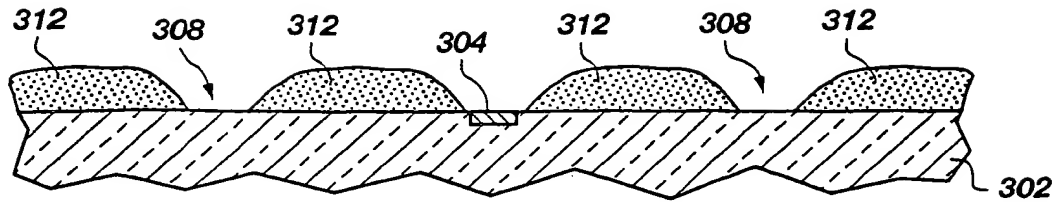


Fig. 46
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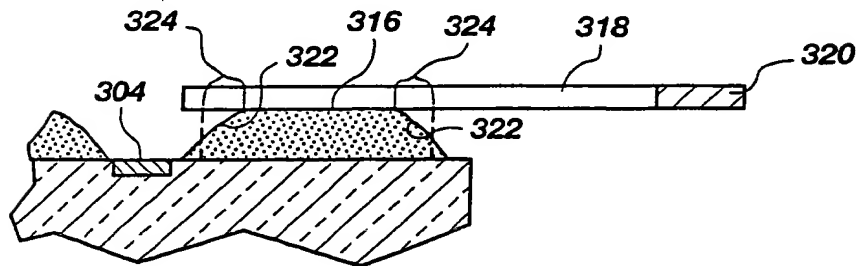


Fig. 47
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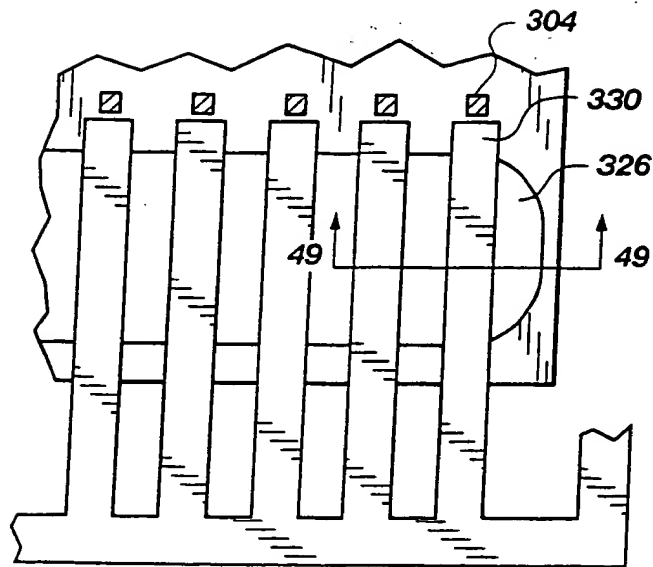


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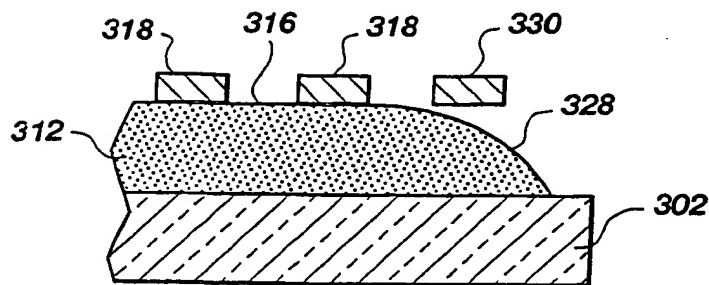


Fig. 49
(PRIOR ART)

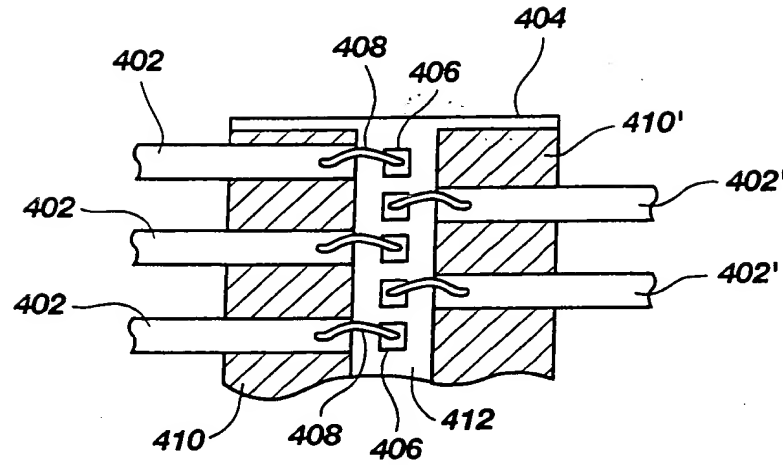


Fig. 50
(PRIOR ART)

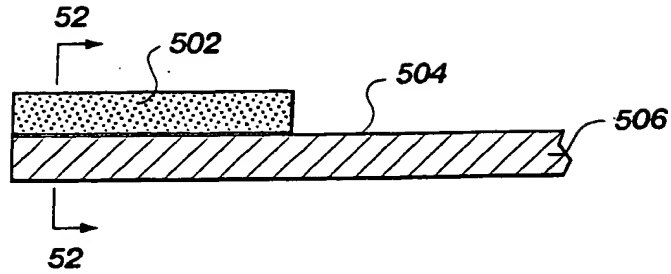


Fig. 51
(PRIOR ART)

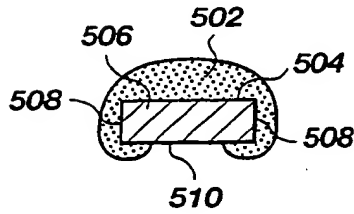


Fig. 52
(PRIOR ART)

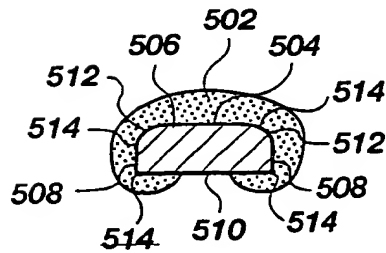


Fig. 53
(PRIOR ART)

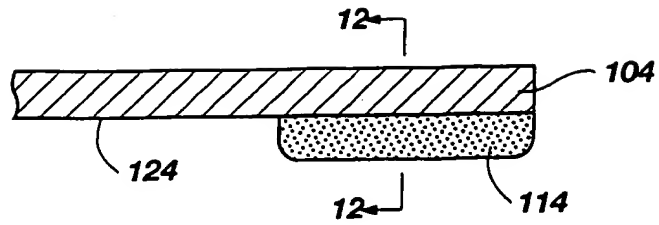


Fig. 11

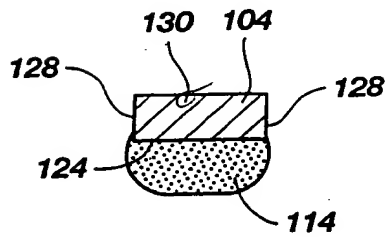


Fig. 12

Shorten lead line
to stop at
"surface"

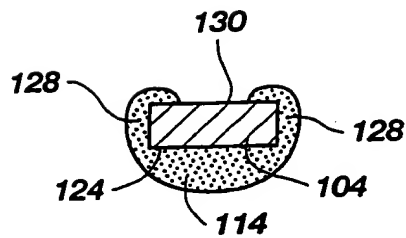


Fig. 13